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To the Honorable Commissioner of Patents and Trademarks. Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):
Jin-Sik CHOIAdditional name(s) of conveying
party(ies) attached? ☐ Yes ☒ No

2. Name and address of receiving party(ies):

NAME: KOMICO Co., LTD.

ADDRESS: 3F Cheongryong Building, 696-1 Gomae-ri,
Kiheung-eup, Yongin-city, Kyungki-do,
Republic of KoreaAdditional name(s) & addresses(es) attached?
☐ Yes ☒ No

3. Name of Conveyance:

☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other

Execution/Effective Date: December 5, 2002

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: _____

A. Patent Application No.(s)

10/309325

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☐ No5. Name and address of party to whom correspondence
concerning document should be mailed:

Name: G. Franklin Rothwell
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Attorney Docket No. : 1751-316

6. Total number of applications
and patents involved: _____

One

7. Total fee (37 CFR 3.41): . . . \$ 40.00

☒ Enclosed
☐ Authorized to be charged to deposit account

8. Deposit account number: 02-2135

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a
true copy of the original document.

G. Franklin Rothwell

Name of Person Signing

G.F. Rothwell

Signature

3.20.03

Date

Total number of pages including cover sheet, attachments and documents: 2

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ASSIGNMENT OF PATENT APPLICATION**WHEREAS**, I/We, CHOI, Jin-Sik, a citizen of Republic of Korea.*First Named Inventor*residing at 116-903 Unamjugong Apt., Busan-dong, Osan-city, Kyungki-do, Rep. of Korea.*Address*ASSIGNOR(S), am/are the inventor(s) of an invention in (insert title)**METHOD OF FABRICATING AND REPAIRING CERAMIC COMPONENTS
FOR SEMICONDUCTOR FABRICATION USING PLASMA SPRAY PROCESS**

for which I/we have executed an application for Letters Patent of the United States,

(Check One) ☒ of even date herewith:
☐ U.S. Serial Number _____ filed _____;
☐ International Application No. _____ filed _____.

and

WHEREAS, KOMICO Co., LTD. a Korean Corporation of 3F Cheongryong Building, 696-1 Gomae-ri, Kihung-eup, Yongin-city*Assignee**citizenship or Corporate Situs**address*Kyungki-do, Rep. of Korea**ASSIGNEES**, are desirous of obtaining the entire right, title and interest in, to and under the said invention and the said application;

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) to me/us in hand paid, and other good and valuable consideration, the receipt of which is hereby acknowledged, I/we, the said **ASSIGNOR(S)** have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said **ASSIGNEE**, its successors, legal representatives and assigns, the entire right, title and interest in, to and under the said invention, and the said application and all divisions, renewals and continuations thereof, and all Letters Patent of the United States which may be granted thereon and all reexamination certificates, reissues and extensions thereof, and I/we hereby authorize and request the Commissioner of Patents of the United States, to issue all Letters Patent for said invention to the said **ASSIGNEE**, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND I/WE HEREBY covenant that I/we have the full right to convey the entire interest herein assigned, and that I/we have not executed, and will not execute, any agreement in conflict herewith.

AND I/WE HEREBY further covenant and agree that I/we will communicate to said **ASSIGNEE**, its successors, legal representatives and assigns, any facts known to me/us respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything possible to aid the said **ASSIGNEE**, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention at the expense of the **ASSIGNEES**.

IN TESTIMONY WHEREOF, I/we hereunto set my/our hand(s) and seal(s) the day and year set opposite my/our signature(s).

CHOI, Jin-Sik Jin-Sik Choi L.S. Date 5 December, 2002

L.S. Date _____, 20____

L.S. Date _____, 20____

Witness:

Jeon, Yong-Hee Yong-Hee Jeon 6 December 2002
Name Date
Lee, Ji-Eun Ji-Eun Lee 6 December 2002
Name Date

*Foreign Inventor Sole Joint Assignment
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